TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor SCHS250A

CD54/74AC280, CD54/74ACT280

August 1998 - Revised May 2000

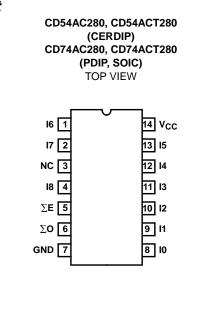
Features

- Buffered Inputs
- Typical Propagation Delay
 - 10ns at V_{CC} = 5V, T_A = 25^oC, C_L = 50pF
- Exceeds 2kV ESD Protection per MIL-STD-883, Method 3015
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
- Balanced Propagation Delays
- AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- ±24mA Output Drive Current
 - Fanout to 15 FAST™ ICs
 - Drives 50 Ω Transmission Lines

Description

The 'AC280 and 'ACT280 are 9-bit odd/even parity generator/checkers that utilize Advanced CMOS Logic technology. Both even and odd parity outputs are available for checking or generating parity for words up to nine bits long. Even parity is indicated (Σ E output is HIGH) when an even number of





9-Bit Odd/Even Parity Generator/Checker

data inputs is HIGH. Odd parity is indicated (Σ O output is HIGH) when an odd number of data inputs is HIGH. Parity checking for words larger than nine bits can be accomplished by tying the Σ E output to any input of an additional 'AC280, 'ACT280 parity checker.

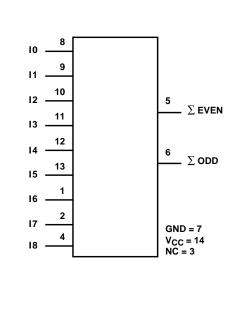
Ordering Information

PART NUMBER	TEMP. RANGE (^O C)	PACKAGE
CD54AC280F3A	-55 to 125	14 Ld CERDIP
CD74AC280E	0 to 70 ⁰ C, -40 to 85, -55 to 125	14 Ld PDIP
CD74AC280M	0 to 70 ⁰ C, -40 to 85, -55 to 125	14 Ld SOIC
CD54ACT280F3A	-55 to 125	14 Ld CERDIP
CD74ACT280E	0 to 70 ⁰ C, -40 to 85, -55 to 125	14 Ld PDIP
CD74ACT280M	0 to 70 ⁰ C, -40 to 85, -55 to 125	14 Ld SOIC

NOTES:

- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- 2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.





CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

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Absolute Maximum Ratings

DC Supply Voltage, V _{CC}
DC Input Diode Current, I _{IK}
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ ±20mA
DC Output Diode Current, I _{OK}
For $V_0 < -0.5V$ or $V_0 > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_{O} > -0.5V$ or $V_{O} < V_{CC} + 0.5V$
DC V _{CC} or Ground Current, $I_{CC or} I_{GND}$ (Note 3) ±100mA
Operating Conditions

Temperature Rar	nge, T _A	55 ⁰ C to 125 ⁰ C
Supply Voltage R	ange, V _{CC} (Note 4)	
AC Types		1.5V to 5.5V
ACT Types		4.5V to 5.5V
DC Input or Outp	ut Voltage, VI, VO	0V to V _{CC}
Input Rise and Fa	all Slew Rate, dt/dv	
AC Types, 1.5	/ to 3V	50ns (Max)
AC Types, 3.6	/ to 5.5V	20ns (Max)
ACT Types, 4.8	5V to 5.5V	10ns (Max)

Thermal Information

Thermal Resistance (Typical, Note 5)	θ _{JA} (^o C/W)
PDIP Package	
SOIC Package	
Maximum Junction Temperature (Plastic Package)	150 ⁰ C
Maximum Storage Temperature Range	65 ⁰ C to 150 ⁰ C
Maximum Lead Temperature (Soldering 10s)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

3. For up to 4 outputs per device, add $\pm 25 \text{mA}$ for each additional output.

4. Unless otherwise specified, all voltages are referenced to ground.

5. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

		TEST CONDITIONS		Vcc	25 ⁰ C		-40°C TO 85 ⁰ C		-55 [°] C TO 125 [°] C		
PARAMETER	SYMBOL	V _I (V)	l _O (mA)	(Ň)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
AC TYPES											
High Level Input Voltage	VIH	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	VIL	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	VOH	V _{IH} or V _{IL}	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

DC Electrical Specifications (Continued) TEST -40°C TO -55⁰C TO CONDITIONS 25°C 85⁰C 125°C Vcc PARAMETER SYMBOL V_I (V) I_O (mA) (V) MIN MAX MIN MAX MIN MAX UNITS Low Level Output Voltage 0.05 0.1 0.1 1.5 0.1 V VOL VIH or VIL ---0.05 3 0.1 0.1 V -0.1 --0.05 4.5 -0.1 -0.1 -0.1 V 12 3 0.36 0.44 0.5 V ---24 4.5 0.36 0.44 -0.5 V --75 5.5 _ 1.65 -_ V _ _ (Note 6, 7) 50 5.5 V 1.65 -----(Note 6, 7) Input Leakage Current h. 5.5 ±0.1 ±1 V_{CC} or ----±1 μΑ GND **Quiescent Supply Current** V_{CC} or 0 5.5 _ 8 80 _ 160 μΑ ICC _ MSI GND ACT TYPES V High Level Input Voltage VIH _ -4.5 to 2 -2 -2 -5.5 Low Level Input Voltage 4.5 to 0.8 0.8 V V_{IL} 0.8 -----5.5 VIH or VIL V High Level Output Voltage Vон -0.05 4.5 4.4 4.4 4.4 ---24 4.5 3.94 -3.8 -3.7 -V -75 5.5 3.85 V --(Note 6, 7) -50 5.5 3.85 V ---_ -(Note 6, 7) VOL Low Level Output Voltage 0.05 4.5 0.1 0.1 0.1 V VIH or VIL ---24 4.5 0.36 0.44 -0.5 V --75 5.5 1.65 V _ --_ -(Note 6, 7) 50 5.5 1.65 V -----(Note 6, 7) Input Leakage Current h. V_{CC} or 5.5 -±0.1 -±1 -±1 μΑ -GND **Quiescent Supply Current** V_{CC} or 0 5.5 8 80 _ 160 ICC -_ μΑ MSI GND Additional Supply Current per 4.5 to 2.4 2.8 3 ∆lcc Vcc ---mΑ Input Pin TTL Inputs High -2.1 5.5 1 Unit Load

NOTES:

6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

7. Test verifies a minimum 50Ω transmission-line-drive capability at 85° C, 75Ω at 125° C.

ACT Input Load Table

INPUT	UNIT LOAD
All	1.43

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

			-40	°C TO 85°	С	-55			
PARAMETER	SYMBOL	v _{cc} (v)	MIN	TYP	MAX	MIN	TYP	MAX	
AC TYPES									
Propagation Delay,	t _{PLH} , t _{PHL}	1.5	-	-	239	-	-	263	ns
Any Input to ΣO		3.3 (Note 9)	7.5	-	26	7.3	-	29	ns
		5 (Note 10)	5.4	-	19.1	5.3	-	21	ns
Propagation Delay,	t _{PLH} , t _{PHL}	1.5	-	-	227	-	-	250	ns
Any Input to ∑E		3.3	7.2	-	25	7	-	28	ns
		5	5.2	-	18.2	5	-	20	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	-	-	115	-	-	115	-	pF
ACT TYPES									
Propagation Delay, Any Input to ΣO	t _{PLH} , t _{PHL}	5 (Note 10)	5.6	-	19.6	5.4	-	21.6	ns
Propagation Delay, Any Input to ΣE	t _{PLH} , t _{PHL}	5	5.6	-	19.6	5.4	-	21.6	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	-	-	115	-	-	115	-	pF

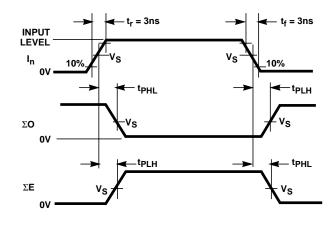
NOTES:

8. Limits tested 100%

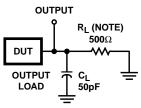
9. 3.3V Min is at 3.6V, Max is at 3V.

10. 5V Min is at 5.5V, Max is at 4.5V.

11. C_{PD} is used to determine the dynamic power consumption per package. AC: $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ ACT: $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency, C_L = output load capacitance, V_{CC} = supply voltage.







NOTE: For AC Series Only: When V_{CC} = 1.5V, R_L = 1k $\!\Omega.$

	AC	ACT
Input Level	V _{CC}	3V
Input Switching Voltage, V _S	0.5 V _{CC}	1.5V
Output Switching Voltage, V _S	0.5 V _{CC}	0.5 V _{CC}

FIGURE 2. PROPAGATION DELAY TIMES



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CD54AC280F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC280F3A	Samples
CD54ACT280F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT280F3A	Samples
CD74AC280E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC280E	Samples
CD74AC280M	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC280M	Samples
CD74AC280M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC280M	Samples
CD74AC280M96G4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC280M	Samples
CD74ACT280E	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT280E	Samples
CD74ACT280M	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT280M	Samples
CD74ACT280M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT280M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54AC280, CD54ACT280, CD74AC280, CD74ACT280 :

• Catalog : CD74AC280, CD74ACT280

• Military : CD54AC280, CD54ACT280

NOTE: Qualified Version Definitions:

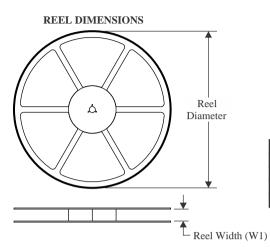
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

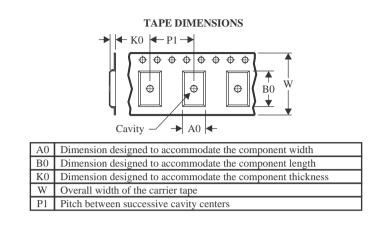


Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



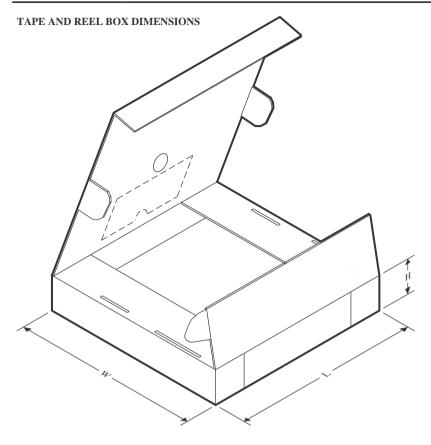
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC280M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74ACT280M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

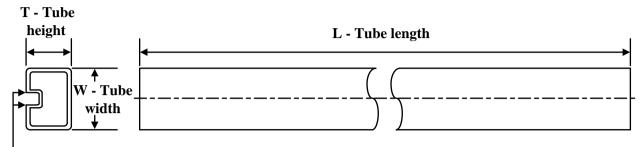
Device	Package Type	Package Type Package Drawing Pins SPQ Le		Length (mm)	Width (mm)	Height (mm)	
CD74AC280M96	SOIC	D	14	2500	356.0	356.0	35.0
CD74ACT280M96	SOIC	D	14	2500	356.0	356.0	35.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74AC280E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC280E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC280M	D	SOIC	14	50	506.6	8	3940	4.32
CD74ACT280E	N	PDIP	14	25	506	13.97	11230	4.32
CD74ACT280E	N	PDIP	14	25	506	13.97	11230	4.32
CD74ACT280M	D	SOIC	14	50	506.6	8	3940	4.32

GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.

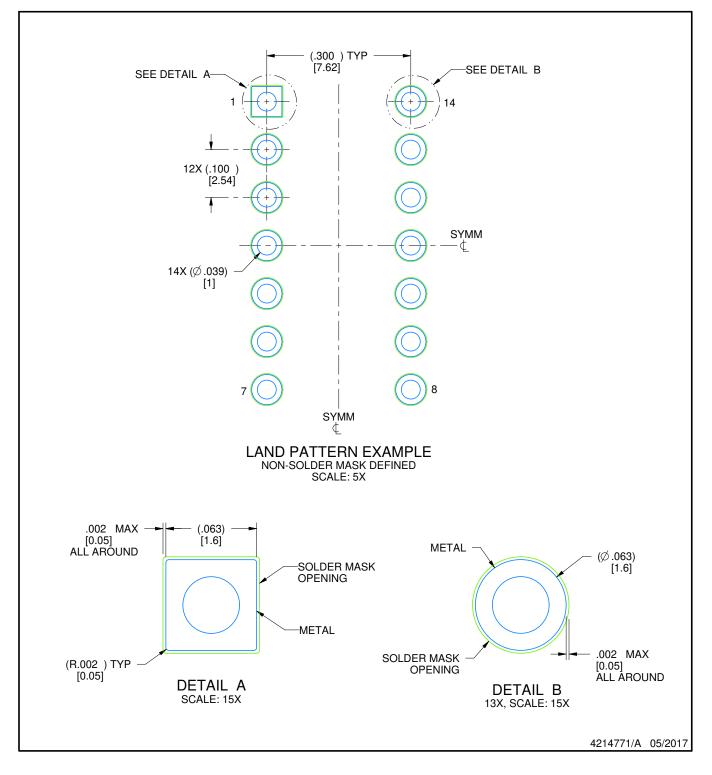


J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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